

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/12/2022

Details for "TPS7A0512PDQNR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS7A0512PDQNR	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DQN 4	1x1x0.37	1.1

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Not Categorized	Proprietary Materials		0.000001	0.013637	136	0.000093	1
Precious Metals	Gold	7440-57-5	0.007332	99.986363	999864	0.680408	6804
Sub-Total			0.007333	100	1000000	0.680501	6805
Die Attach Adhesive							
Other Nonferrous Metals and Alloys	Titanium Dioxide	13463-67-7	0.000629	3.001241	30012	0.058371	584
Thermoplastics	Epoxy	85954-11-6	0.020329	96.998759	969988	1.886528	18865
Sub-Total			0.020958	100	1000000	1.944899	19449
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	0.316276	74	740000	29.350364	293504
Nickel and Its Alloys	Nickel	7440-02-0	0.035175	8.229995	82300	3.264235	32642
Thermoplastics	Epoxy	85954-11-6	0.075949	17.770005	177700	7.048055	70481
Sub-Total			0.4274	100	1000000	39.662654	396627
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.121754	95.120313	951203	11.298752	112988
Precious Metals	Gold	7440-57-5	0.000998	0.779688	7797	0.092614	926
Precious Metals	Palladium	7440-05-3	0.005248	4.1	41000	0.487014	4870
Sub-Total			0.128	100	1000000	11.87838	118784
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	0.342838	84.809879	848099	31.815313	318153
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	0.021021	5.20009	52001	1.950746	19507
Other Plastics and Rubber	Carbon Black	1333-86-4	0.000849	0.210022	2100	0.078787	788
Thermoplastics	Epoxy	85954-11-6	0.039535	9.780009	97800	3.668842	36688
Sub-Total			0.404243	100	1000000	37.513688	375137
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.089654	100	1000000	8.319877	83199
Sub-Total			0.089654	100	1000000	8.319877	83199
Total			1.077588			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.